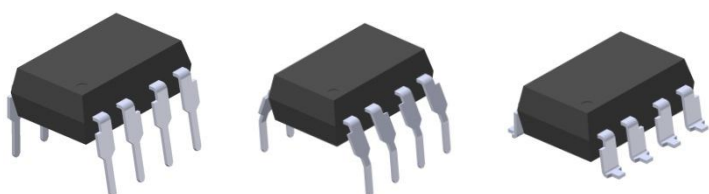
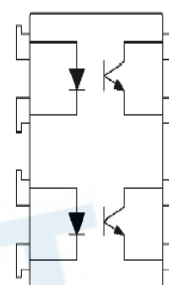


## 8 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL827 Series



Schematic



Pin Configuration

1, 3. Anode  
2, 4. Cathode  
5, 7. Emitter  
6, 8. Collector

### Features:

- Current transfer ratio  
(CTR: 50~600% at  $I_F = 5\text{mA}$ ,  $V_{CE} = 5\text{V}$ )
- High isolation voltage between input and output (Viso=5000 V rms )
- Compact small outline package
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

### Description

The EL827series devices each of consist of an infrared emitting diodes, optically coupled to a phototransistor detector. They are packaged in a 8-pin DIP package and available in wide-lead spacing and SMD option.

### Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

**Absolute Maximum Ratings (Ta=25°C)**

	Parameter	Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	60	mA
	Peak forward current (1us, pulse)	I <sub>FP</sub>	1	A
	Reverse voltage	V <sub>R</sub>	6	V
	Power dissipation	P <sub>D</sub>	100	mW
Output	Power dissipation	P <sub>C</sub>	150	mW
	Collector current	I <sub>C</sub>	50	mA
	Collector-Emitter voltage	V <sub>CEO</sub>	80	V
	Emitter-Collector voltage	V <sub>ECO</sub>	7	V
	Total power dissipation	P <sub>TOT</sub>	200	mW
	Isolation voltage <sup>*1</sup>	V <sub>ISO</sub>	5000	V rms
	Operating temperature	T <sub>OPR</sub>	-55 to 110	°C
	Storage temperature	T <sub>STG</sub>	-55 to 125	°C
	Soldering temperature <sup>*2</sup>	T <sub>SOL</sub>	260	°C

Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 & 3, 4 are shorted together, and pins 5, 6 & 7, 8 are shorted together.

\*2 For 10 seconds

**Electro-Optical Characteristics (Ta=25°C unless specified otherwise)**

**Input**

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Forward Voltage	$V_F$	-	1.2	1.4	V	$I_F = 20\text{mA}$
Reverse Current	$I_R$	-	-	10	$\mu\text{A}$	$V_R = 4\text{V}$
Input capacitance	$C_{in}$	-	30	250	pF	$V = 0, f = 1\text{kHz}$

**Output**

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Collector-Emitter dark current	$I_{CEO}$	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	$BV_{CEO}$	80	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	$BV_{ECO}$	7	-	-	V	$I_E = 0.1\text{mA}$

**Transfer Characteristics**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	CTR	50	-	600	%	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-	0.1	0.2	V	$I_F = 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	$R_{IO}$	$5 \times 10^{10}$	-	-	$\Omega$	$V_{IO} = 500\text{Vdc}, 40\sim 60\% \text{ R.H.}$
Floating capacitance	$C_{IO}$	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Cut-off frequency	$f_c$	-	80	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$
Rise time	$t_r$	-	3	18	$\mu\text{s}$	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$
Fall time	$t_f$	-	4	18	$\mu\text{s}$	

\* Typical values at  $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves

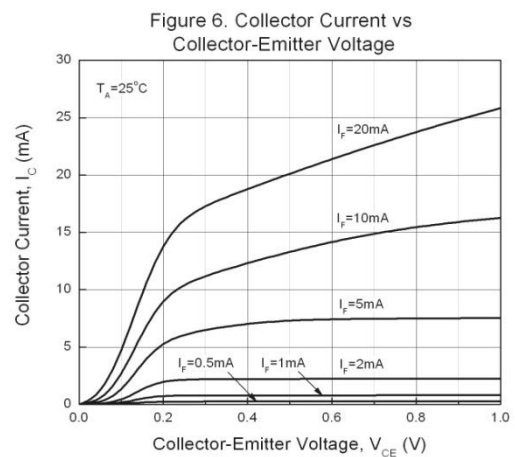
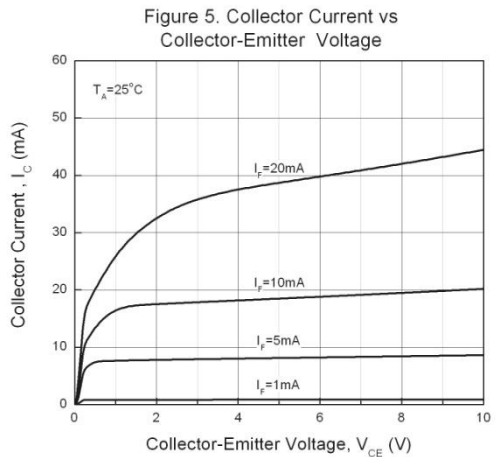
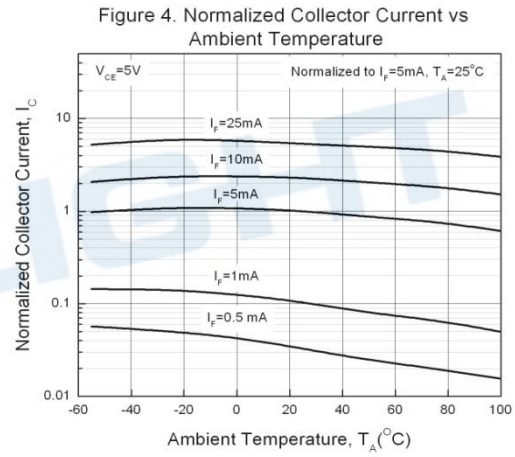
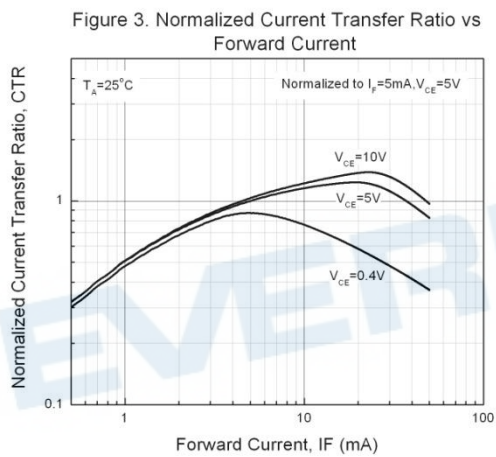
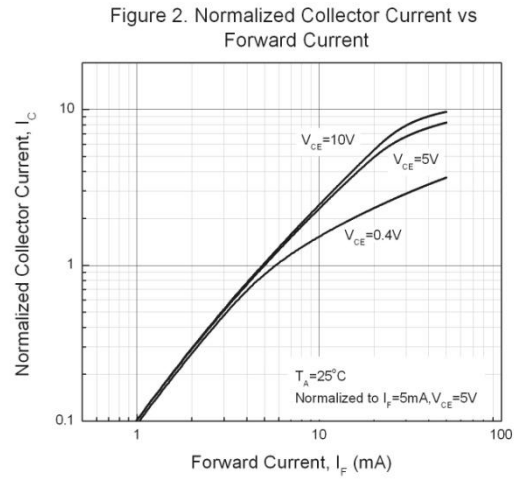
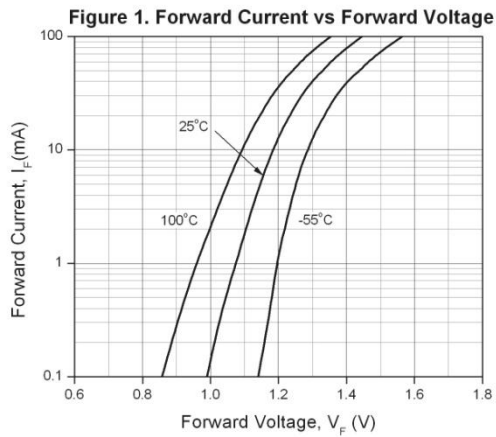


Figure 7. Collector Dark Current vs Ambient Temperature

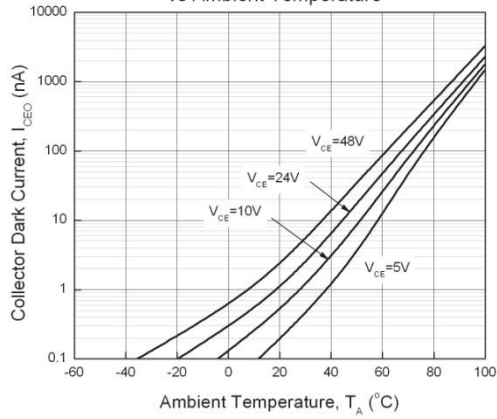


Figure 8. Switching Time vs Load Resistance

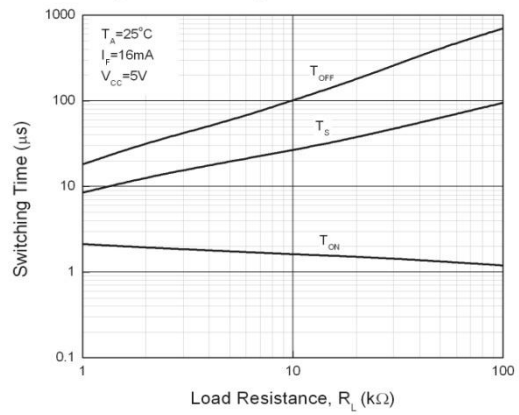


Figure 9. Collector-Emitter Saturation Voltage vs Ambient Temperature

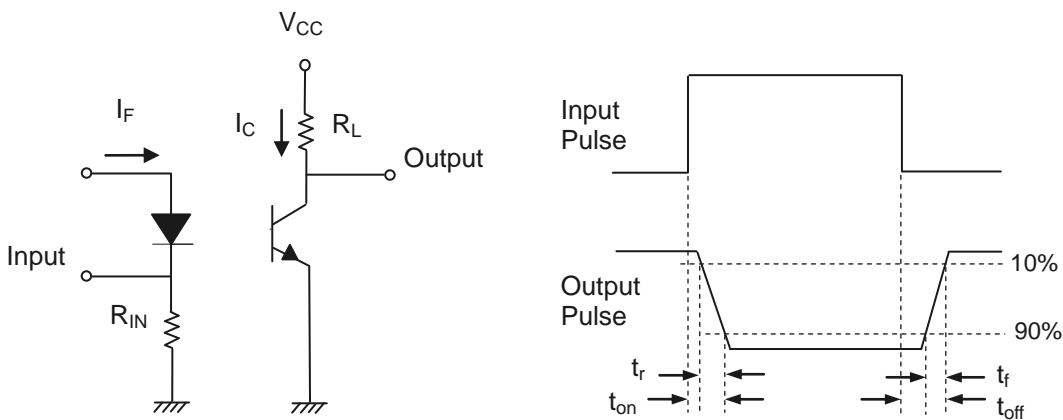
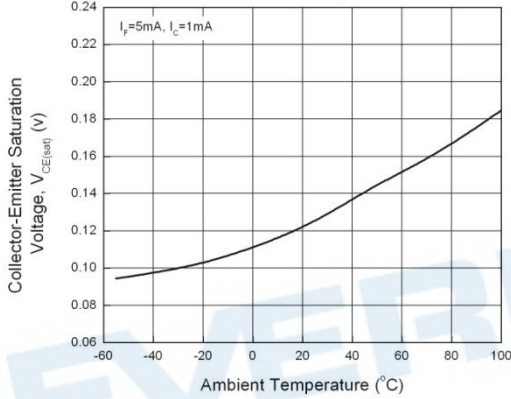


Figure 10. Switching Time Test Circuit & Waveforms

## Order Information

### Part Number

**EL827X(Z)-V**

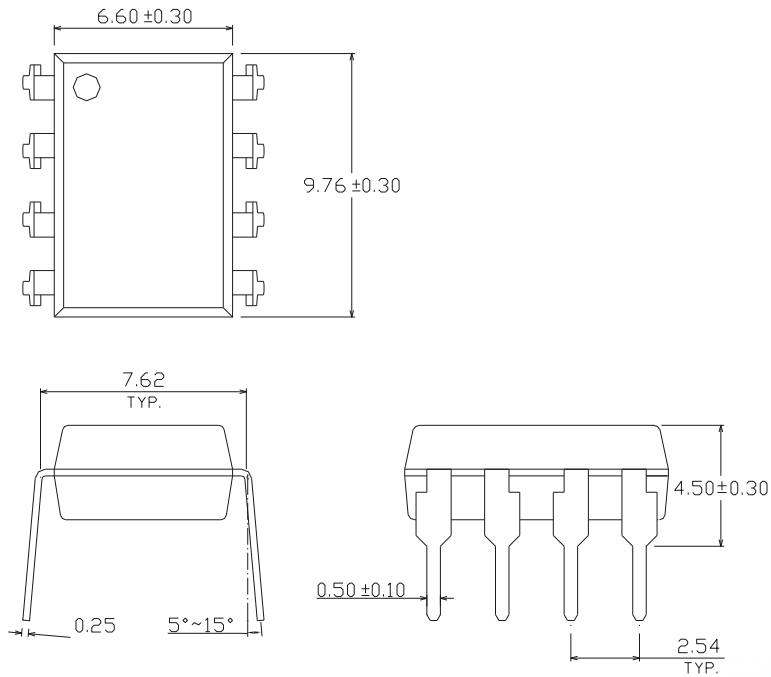
### Note

- X = Lead form option (S, S1, M or none)
- Z = Tape and reel option (TA, TB or none)
- V = VDE safety (optional)

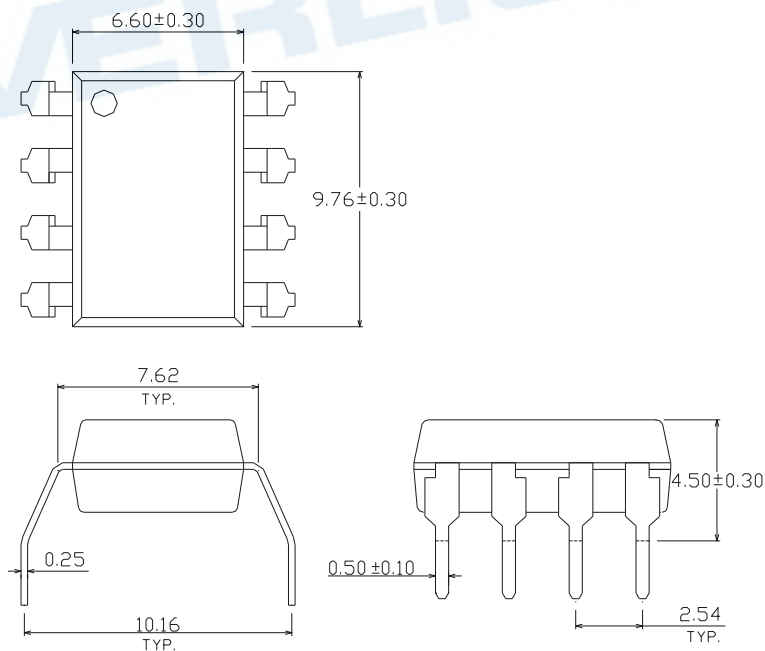
Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
M	Wide lead bend (0.4 inch spacing)	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

### Package Dimension (Dimensions in mm)

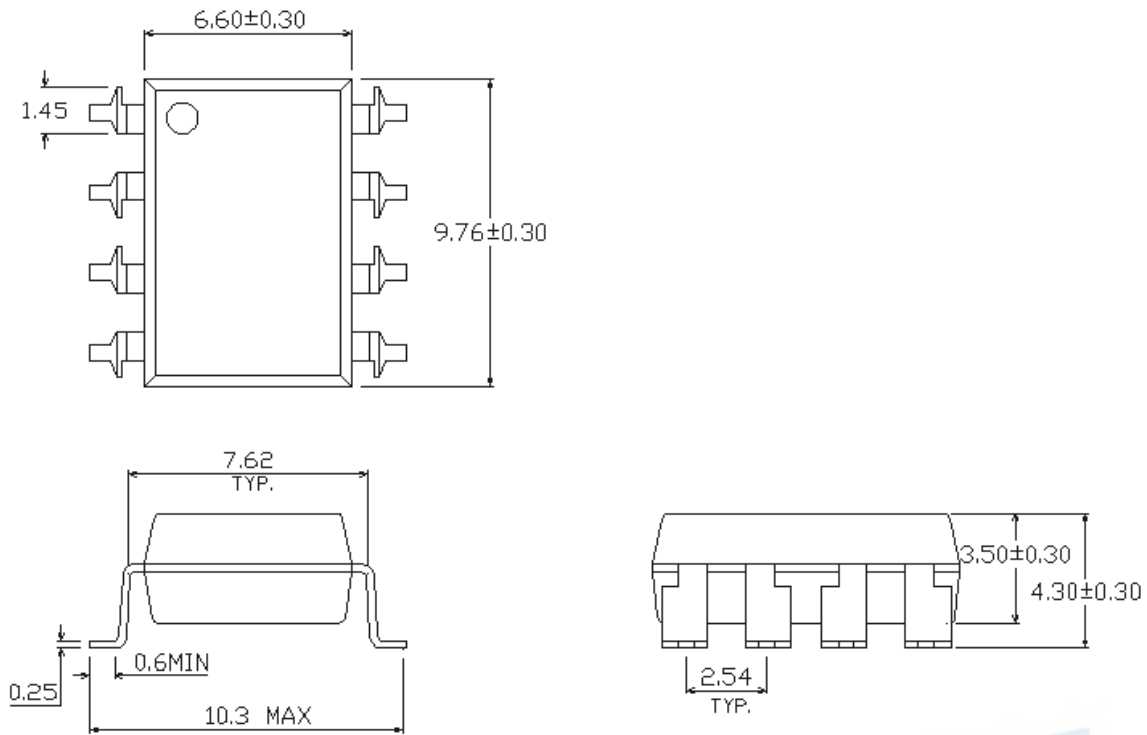
#### Standard DIP Type



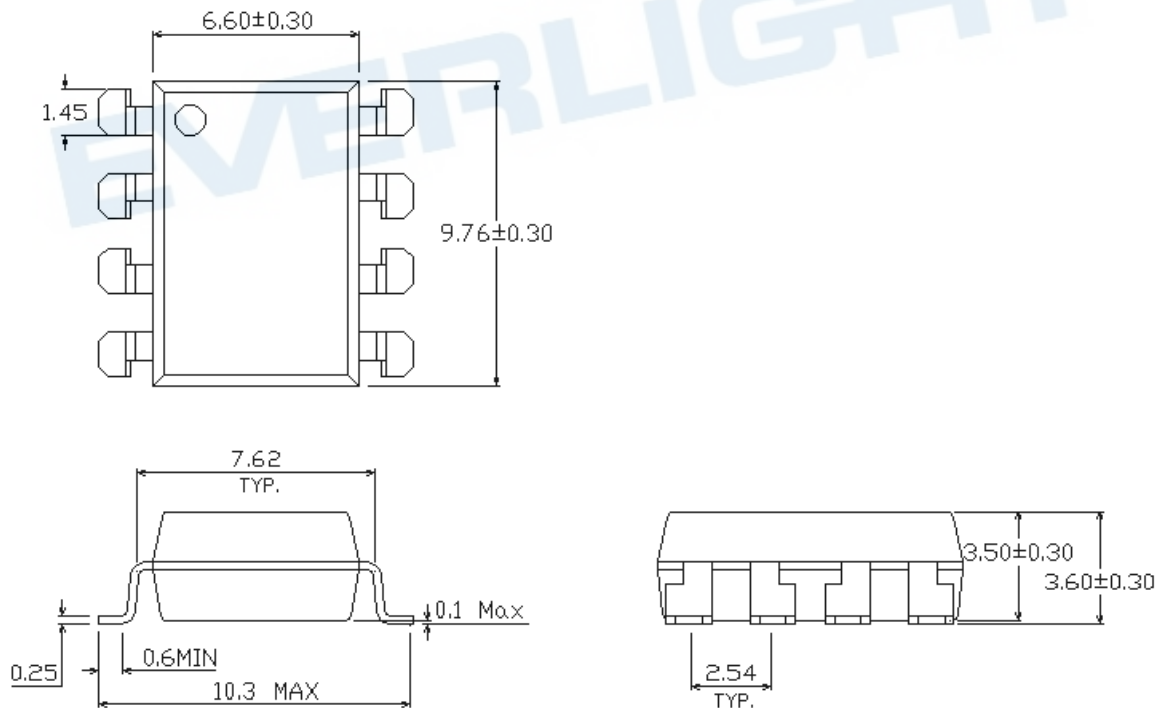
#### Option M Type



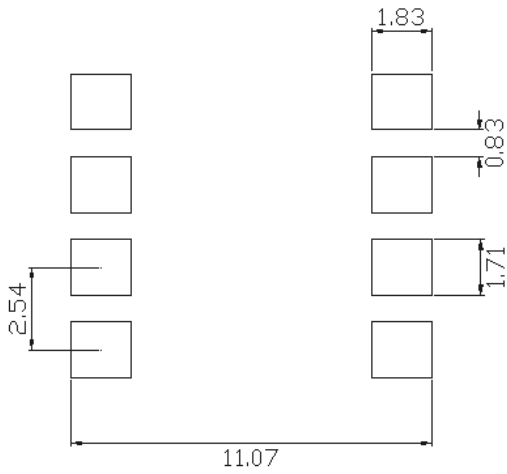
Option S Type



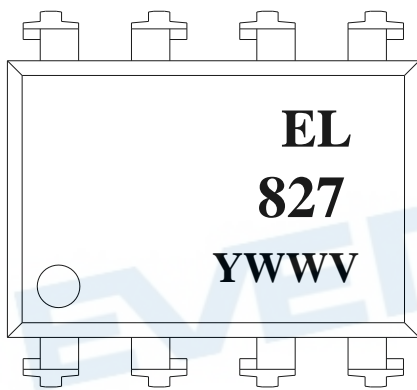
Option S1 Type



Recommended pad layout for surface mount leadform



Device Marking

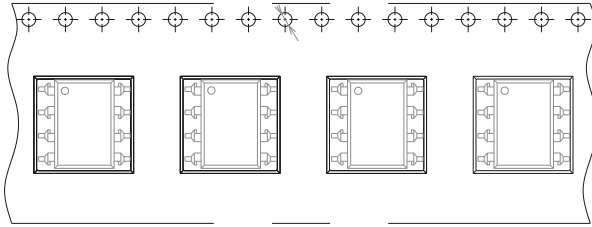


Notes

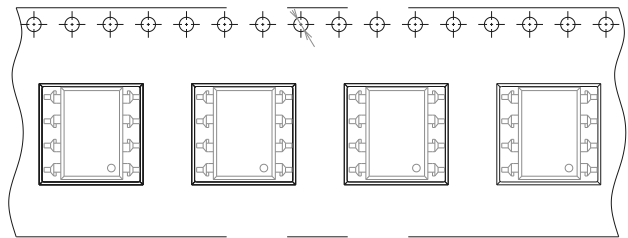
- EL827 denotes Device Number
- Y denotes 1 digit Year code
- WW denotes 2 digit Week code
- V denotes VDE (optional)

**Tape & Reel Packing Specifications**

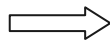
**Option TA**



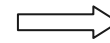
**Option TB**



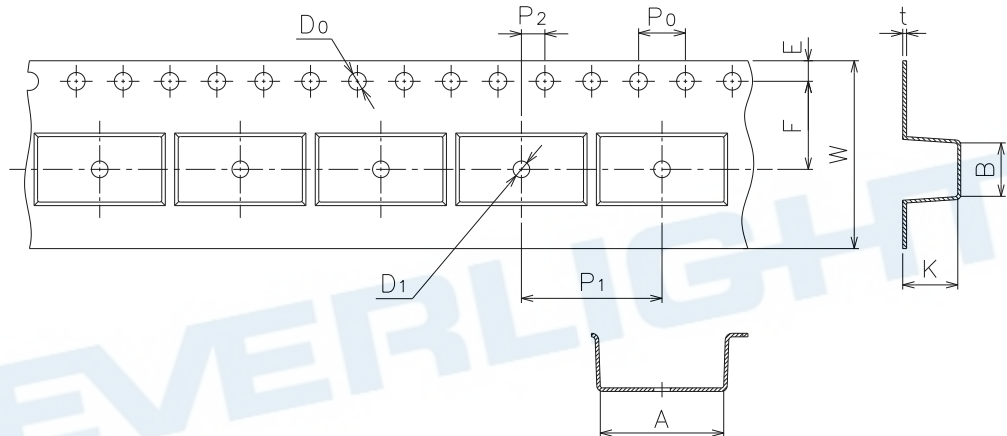
Direction of feed from reel



Direction of feed from reel



**Tape dimensions**

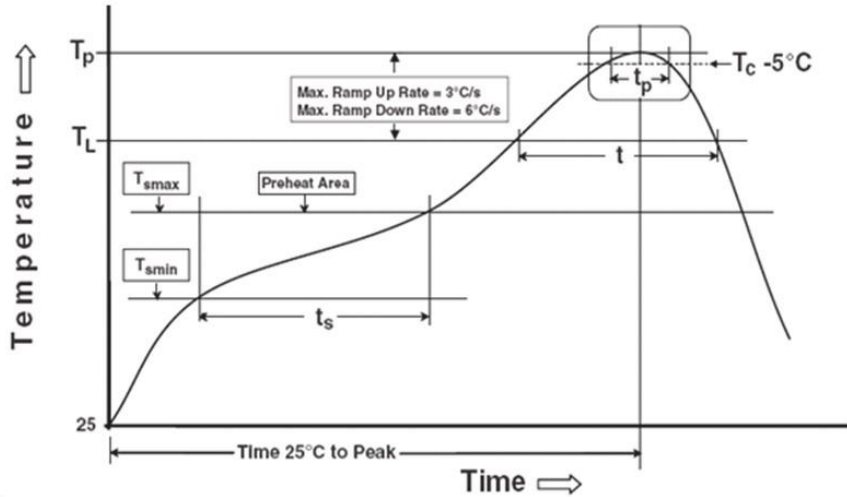


Dimension No.	<b>A</b>	<b>B</b>	<b>Do</b>	<b>D1</b>	<b>E</b>	<b>F</b>
Dimension(mm)	10.4±0.1	10.0±0.1	1.5±0.1	1.5+0.25 -0.1	1.75±0.1	7.5±0.1
Dimension No.	<b>Po</b>	<b>P1</b>	<b>P2</b>	<b>t</b>	<b>W</b>	<b>K</b>
Dimension(mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	4.5±0.1

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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